Monday 30 Sept.

Time	Event
9:30 – 12:30	15th European FIB Users Group Meeting, EFUG workshop
14:00 – 18:00	15th European FIB Users Group Meeting, EFUG workshop

Tuesday 1 October

Time	Event
8:50 – 10:30	**Tutorial** "Failure Analysis Techniques for a Three-Dimensional World"
10:30 – 10:50	Coffee break
10:50 – 12:30	**Tutorial** "Dielectric Breakdown in High-k/Metal Stacks"
10:50 – 12:30	**Tutorial** "Rel. of embedding active and passive components in an interconnect substrate"
12:30 – 14:00	Lunch
14:00 – 14:20	Conf. Opening
14:20 – 15:00	**Invited** "Sub-28nm FD-SOI Technologies"
15:00	Best Paper IRPS
15:40	Best Paper IPFA
15:40 – 16:00	Coffee break
16:00 – 16:40	**Invited** B3
16:40 – 18:00	Session B3a: EOS/ESD/EMC Robustness, Modeling and Characterization
16:40 – 20:00	Workshop "Accelerated mechanical testing for reliability assessment in microelectronic applications"

Wednesday 2 October

Time	Event
8:30 – 9:10	**Invited** F
9:10 – 10:30	Session Fa: Lifetime testing & monitoring of Power devices
9:10 – 10:30	Session Ca: Failure analysis, Optical techniques
9:10 – 10:30	Session B3b: Radiation Effects Modeling
10:30 – 10:50	Coffee break
10:50 – 11:30	**Invited** C
11:30 – 12:30	Session Cb: Failure analysis, Sample preparation
11:30 – 12:30	Session B3c: Radiation effects characterization & mitigation
12:30 – 14:00	Lunch
14:00 – 14:40	**Invited** G
14:40 – 16:00	Session G: Reliability of Photovoltaic and Organic devices
14:40 – 16:00	Session Fb: Testing and modeling of Si devices
14:40 – 16:00	Session Cc: Failure analysis, Magnetic & Near-field techniques
16:00 – 16:20	Coffee break
16:20 – 18:00	Poster session
18:00 – 20:00	Workshop EUFANET
18:00 – 20:00	Workshop "Power devices"

Thursday 3 October

Time	Event
8:30 – 9:10	**Invited** D1
9:10 – 10:30	Session D1a: Failures mechanisms in Microwave and Wide Band-Gap Devices
9:10 – 10:30	Session B1: Failure mechanism in Si & Nanoelectronics
9:10 – 10:30	Session Aa: Reliability techniques at function level
10:30 – 10:50	Coffee break
10:50 – 11:30	**Invited** D2
11:30 – 12:30	Session D2a: Failures mechanisms in Photonic Devices
11:30 – 12:30	Session B1B2: Failure mechanism in Si & Nanoelectronics
11:30 – 12:30	Session Ab: Reliability techniques at component level
12:30 – 14:00	Lunch
14:00 – 14:40	**Invited** E1
14:40 – 16:00	Session E1a: Degradation mechanisms of semiconductor / substrate joints
14:40 – 16:00	Session Fc: Test and modeling of SiC devices
14:40 – 16:00	Case study Workshop
16:00 – 16:20	Coffee break
16:20 – 17:40	Session E1b: Degradation mechanisms of packages and solder interconnects
16:20 – 18:00	Session Fd: Thermal management & packaging
16:20 – 17:40	Case study Workshop

Friday 4 October

Time	Event
8:30 – 9:10	**Invited** E2
9:10 – 10:30	Session E2a: Passive devices reliability
9:10 – 10:30	Session D1b: Failures mechanisms in Microwave and Wide Band-Gap devices
10:30 – 10:50	Coffee break
10:50 – 12:10	Session E2b: MEMS reliability
10:50 – 12:10	Session D2b: Failure mechanisms in Photonic devices
12:10 – 13:00	BPA and closing

Key-note: Sub-28nm FD-SOI Technologies

Invited papers

B3: Long-term Electro-Magnetic Robustness of Integrated Circuits: EMRIC research project
F: Trends in automotive power semiconductor packaging
C: Effectiveness of the scanning nonlinear dielectric microscopy on the FA of devices
G: Thin film silicon photovoltaics from glass substrates to flexible organic/plastic substrates
D1: Qualification of 50V GaN on SiC technology for RF Power amplifiers
D2: High optical strength GaAs-based laser structures
E1: Application of advanced reliability and FA methods for eWLB Fan-Out WLP Technology
E2: MEMS packaging reliability assessment: Residual Gas Analysis of gaseous species